P29124.A02.Dob

TATES PATENT AND TRADEMARK OFFICE

: Akihiko ENDO et al. **Applicants**

Group Art Unit: Not Yet Assigned

Appl. No.

: 10/570,668

(U.S. National Stage of PCT/JP2004/013070)

I.A. Filed

:September 8, 2004

Examiner: Not Yet Assigned

For

: SOI WAFER AND ITS MANUFACTURING METHOD

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents U.S. Patent and Trademark Office Customer Service Window, Mail Stop AMENDMENT Randolph Building 401 Dulany Street Alexandria, VA 22314

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56 and §§1.97-1.98, Applicants hereby bring the following information to the attention of the Examiner, which includes information cited and discussed in the specification and the International Search Report issued in connection with International Patent Application No. PCT/JP2004/013070, of which the present application is the U.S. National Stage Application. A copy of the International Search Report was enclosed with the papers when entering the U.S. National Stage on March 6, 2006. The Examiner is invited to review these materials to inspect the relevance indicated during international examination with respect to the documents cited therein. The following is a list of the documents cited in the above-noted documents:

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /BS/

/Bradley Smith/

12/15/2008

- Japanese Laid-open Patent Publication No. HEI 9-326396, together with

 an English language abstract and machine translation of the same.

 /Bradley Smith/

 Applicants note that the Japanese document is cited on page 3 of the specification of the present application;
 - Japanese Laid-open Patent Publication No. HEI 2-267195, together with an English language abstract. Applicants note that the Japanese document is cited on page 4 of the specification of the present application;
 - (3) Japanese Laid-open Patent Publication No. 2000-31439, together with an English language abstract and machine translation of the same;
 - (4) Japanese Laid-open Patent Publication No. HEI 9-64319, together with an English language abstract and machine translation of the same; and
 - (5) Japanese Laid-open Patent Publication No. 2001-146498, together with patent family member U.S. Patent No. 6,843,847.

Applicants also call to the Examiner's attention the following documents:

- (6) U.S. Patent Application No. 10/570,665 to ENDO et al., which was filed on March 6, 2006;
- (7) U.S. Patent Application No. 10/570,669 to ENDO et al., which was filed on March 6, 2006;
- (8) U.S. Patent Application No. 10/570,663 to ENDO et al., which was filed on March 6, 2006;
- (9) U.S. Patent Application No. 10/569,942 to ENDO et al., which was filed on February 28, 2006;

- 12/15/2008 (10) U.S. Patent Application No. 10/570,353 to MORIMOTO et al., which was /Bradley Smith/ filed on March 3, 2006; and
 - (11) U.S. Patent Application No. 10/570,354 to MORIMOTO et al., which was filed on March 3, 2006.

Further to 37 C.F.R. §1.98 (a)(2)(ii), a copy of the U.S. patent is not enclosed herewith. However, if a copy is needed, the Examiner is respectfully requested to contact the undersigned.

Further to the U.S. Patent and Trademark Office's decision to waive the requirement under 37 C.F.R. §1.98 (a)(2)(iii) if the U.S. patent applications were filed after June 30, 2003, copies of the U.S. patent applications are not enclosed herewith. However, if any copies are needed, the Examiner is respectfully requested to contact the undersigned.

Applicant respectfully requests that the Examiner consider the above material and cite the same. Copies of the above-noted foreign documents are attached hereto and all of the above-noted documents are listed on the attached PTO-1449 Form. The Examiner is requested to initial the appropriate spaces on the attached Form and to return a copy of the completed Form to Applicants with the next official communication in the present application.

Applicants note that an Office Action on the merits has not issued in the present application, and thus no fee is believed necessary to ensure consideration of the submitted material.

Should the Examiner have any questions, the Examiner is invited to contact the undersigned at the below-listed telephone number.

Respectfully Submitted, Akihiko ENDO et al.

Bruce H. Bernstein

Reg. No. 29,027

June 14, 2006 GREENBLUM & BERNSTEIN, P.L.C. 1950 Roland Clarke Place Reston, VA 20191 (703) 716-1191 Stephen M. Roylance Reg. No. 31,296

/BS/ 5 U.S. Patent Application No. 10/570,665 to ENDO et al., which was filed on March 6, 2006. /BS/ 6 U.S. Patent Application No. 10/570,669 to ENDO et al., which was filed on March 6, 2006. /BS/ 7 U.S. Patent Application No. 10/570,663 to ENDO et al., which was filed on March 6, 2006. 7BS/ 8 U.S. Patent Application No. 10/569,942 to ENDO et al., which was filed on February 28, 2006. /BS/ 9 U.S. Patent Application No. 10/570,353 to MORIMOTO et al., which was filed on March 3, 2006. /BS/ 10 U.S. Patent Application No. 10/570,354 to MORIMOTO et al., which was filed on March 3, 2006.

*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

DATE CONSIDERED

01/16/2009

/Bradley Smith/

EXAMINER